



Attorney's Docket No.: 10417-066001 / F51-129322M/HW

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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FEB 10 2003

Applicant : Noriaki Sakamoto et al.
Serial No. : 09/810,105
Filed : March 16, 2001
Title : SEMICONDUCTOR DEVICE

Art Unit : 2811
Examiner : Parekh, Nitin
TECHNOLOGY CENTER 2800

Commissioner for Patents
Washington, D.C. 20231

AMENDMENT

A RCE was file on November 1, 2002 with a request for suspension, which was granted.
In response to the advisory action mailed October 22, 2002, please amend the application as follows:

In the claims:

Please add claims 17 to 25.

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B1
-- 17. (New) A semiconductor device comprising:
a semiconductor chip; and
a plurality of conductive paths electrically separated by a trench, the conductive paths comprising a die pad shape disposed below and substantially at the center of the semiconductor chip, an external connecting shape disposed below the semiconductor chip, and a bonding pad shape disposed beyond the semiconductor chip and being connected to the conductive path of the external connecting shape;

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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